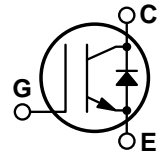
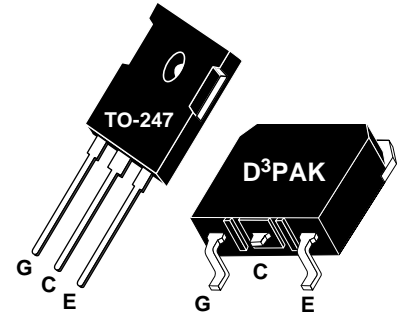


## Fast IGBT & FRED

The Fast IGBT™ is a new generation of high voltage power IGBTs. Using Non-Punch Through Technology the Fast IGBT™ combined with an APT free-wheeling ultraFast Recovery Epitaxial Diode (FRED) offers superior ruggedness and fast switching speed.

- Low Forward Voltage Drop
- Low Tail Current
- RBSOA and SCSOA Rated
- Ultrafast Soft Recovery Antiparallel Diode
- High Freq. Switching to 20KHz
- Ultra Low Leakage Current



### MAXIMUM RATINGS (IGBT)

All Ratings:  $T_C = 25^\circ\text{C}$  unless otherwise specified.

| Symbol         | Parameter   | APT20GF120BRD/SRD | UNIT             |
|----------------|---|-------------------|------------------|
| $V_{CES}$      | Collector-Emitter Voltage   | 1200              | Volts            |
| $V_{CGR}$      | Collector-Gate Voltage ( $R_{GE} = 20\text{K}\Omega$ )                            | 1200              |                  |
| $V_{GE}$       | Gate-Emitter Voltage  | $\pm 20$          |                  |
| $I_{C1}$       | Continuous Collector Current <sup>③</sup> @ $T_C = 25^\circ\text{C}$              | 32                | Amps             |
| $I_{C2}$       | Continuous Collector Current @ $T_C = 105^\circ\text{C}$                          | 20                |                  |
| $I_{CM}$       | Pulsed Collector Current <sup>①</sup> @ $T_C = 90^\circ\text{C}$                  | 64                |                  |
| $I_{LM}$       | RBSOA Clamped Inductive Load Current @ $R_g = 11\Omega$ $T_C = 125^\circ\text{C}$ | 40                |                  |
| $P_D$          | Total Power Dissipation   | 200               | Watts            |
| $T_J, T_{STG}$ | Operating and Storage Junction Temperature Range                                  | -55 to 150        | $^\circ\text{C}$ |
| $T_L$          | Max. Lead Temp. for Soldering: 0.063" from Case for 10 Sec.                       | 300               |                  |

### STATIC ELECTRICAL CHARACTERISTICS (IGBT)

| Symbol       | Characteristic / Test Conditions  | MIN | TYP | MAX       | UNIT  |
|--------------|---|-----|-----|-----------|-------|
| $V_{GE(TH)}$ | Gate Threshold Voltage ( $V_{CE} = V_{GE}$ , $I_C = 600\mu\text{A}$ , $T_j = 25^\circ\text{C}$ )        | 4.5 | 5.5 | 6.5       | Volts |
| $V_{CE(ON)}$ | Collector-Emitter On Voltage ( $V_{GE} = 15\text{V}$ , $I_C = 15\text{A}$ , $T_j = 25^\circ\text{C}$ )  |     | 2.7 | 3.2       |       |
|              | Collector-Emitter On Voltage ( $V_{GE} = 15\text{V}$ , $I_C = 15\text{A}$ , $T_j = 125^\circ\text{C}$ ) |     | 3.3 | 3.9       |       |
| $I_{CES}$    | Collector Cut-off Current ( $V_{CE} = V_{CES}$ , $V_{GE} = 0\text{V}$ , $T_j = 25^\circ\text{C}$ )      |     |     | 1         | mA    |
|              | Collector Cut-off Current ( $V_{CE} = V_{CES}$ , $V_{GE} = 0\text{V}$ , $T_j = 125^\circ\text{C}$ )     |     |     | 6         |       |
| $I_{GES}$    | Gate-Emitter Leakage Current ( $V_{GE} = \pm 20\text{V}$ , $V_{CE} = 0\text{V}$ )                       |     |     | $\pm 100$ | nA    |

**CAUTION:** These Devices are Sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed.

**DYNAMIC CHARACTERISTICS (IGBT)**
**APT20GF120BRD/SRD**

| Symbol       | Characteristic                   | Test Conditions   | MIN | TYP  | MAX  | UNIT |
|--------------|----------------------------------|---|-----|------|------|------|
| $C_{ies}$    | Input Capacitance                | <b>Capacitance</b><br>$V_{GE} = 0V$<br>$V_{CE} = 25V$<br>$f = 1\text{ MHz}$   |     | 1050 | 1210 | pF   |
| $C_{oes}$    | Output Capacitance               |   |     | 100  | 150  |      |
| $C_{res}$    | Reverse Transfer Capacitance     |   |     | 63   | 110  |      |
| $Q_g$        | Total Gate Charge <sup>②</sup>   | <b>Gate Charge</b><br>$V_{GE} = 15V$<br>$V_{CC} = 0.5V_{CES}$<br>$I_C = I_{C2}$   |     | 95   | 140  | nC   |
| $Q_{ge}$     | Gate-Emitter Charge              |   |     | 13   | 20   |      |
| $Q_{gc}$     | Gate-Collector ("Miller") Charge |   |     | 62   | 90   |      |
| $t_{d(on)}$  | Turn-on Delay Time               | <b>Resistive Switching (25°C)</b><br>$V_{GE} = 15V$<br>$V_{CC} = 0.8V_{CES}$<br>$I_C = I_{C2}$<br>$R_G = 10\Omega$  |     | 15   | 30   | ns   |
| $t_r$        | Rise Time                        |   |     | 67   | 130  |      |
| $t_{d(off)}$ | Turn-off Delay Time              |   |     | 92   | 140  |      |
| $t_f$        | Fall Time                        |   |     | 93   | 190  |      |
| $t_{d(on)}$  | Turn-on Delay Time               | <b>Inductive Switching (150°C)</b><br>$V_{CLAMP(Peak)} = 0.66V_{CES}$<br>$V_{GE} = 15V$<br>$I_C = I_{C2}$<br>$R_G = 10\Omega$<br>$T_J = +150^\circ\text{C}$ |     | 17   | 34   | ns   |
| $t_r$        | Rise Time                        |   |     | 30   | 60   |      |
| $t_{d(off)}$ | Turn-off Delay Time              |   |     | 105  | 160  |      |
| $t_f$        | Fall Time                        |   |     | 71   | 140  |      |
| $E_{on}$     | Turn-on Switching Energy         |   |     | 1.3  | 3    |      |
| $E_{off}$    | Turn-off Switching Energy        |   | 1.5 | 3    | mJ   |      |
| $E_{ts}$     | Total Switching Losses           |   | 2.7 | 5    |      |      |
| $t_{d(on)}$  | Turn-on Delay Time               | <b>Inductive Switching (25°C)</b><br>$V_{CLAMP(Peak)} = 0.66V_{CES}$<br>$V_{GE} = 15V$<br>$I_C = I_{C2}$<br>$R_G = 10\Omega$<br>$T_J = +25^\circ\text{C}$   |     | 17   | 30   | ns   |
| $t_r$        | Rise Time                        |   |     | 35   | 70   |      |
| $t_{d(off)}$ | Turn-off Delay Time              |   |     | 93   | 140  |      |
| $t_f$        | Fall Time                        |   |     | 70   | 140  |      |
| $E_{ts}$     | Total Switching Losses           |   |     | 2.4  | 5    |      |
| gfe          | Forward Transconductance         | $V_{CE} = 20V, I_C = 15A$   |     | 12   |      | S    |

**THERMAL AND MECHANICAL CHARACTERISTICS (IGBT and FRED)**

| Symbol          | Characteristic   | MIN | TYP  | MAX  | UNIT  |
|-----------------|--|-----|------|------|-------|
| $R_{\theta JC}$ | Junction to Case (IGBT)  |     |      | 0.63 | °C/W  |
|                 | Junction to Case (FRED)  |     |      | 0.90 |       |
| $R_{\theta JA}$ | Junction to Ambient  |     |      | 40   |       |
| $W_T$           | Package Weight   |     | 0.22 |      | oz    |
|                 |  |     | 6.1  |      | gm    |
| Torque          | Mounting Torque using a 6-32 or 3mm Binding Head Machine Screw |     |      | 10   | lb•in |
|                 |  |     |      | 1.1  | N•m   |

① Repetitive Rating: Pulse width limited by maximum junction temperature.

② See MIL-STD-750 Method 3471

③ Switching losses include the FRED and IGBT.

**APT Reserves the right to change, without notice, the specifications and information contained herein.**

# APT20GF120BRD/SRD

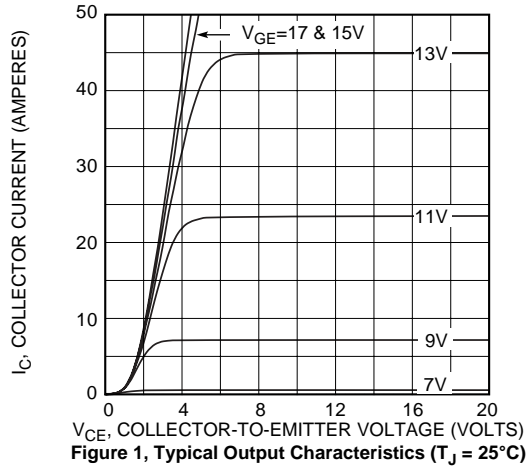


Figure 1, Typical Output Characteristics ( $T_J = 25^\circ\text{C}$ )

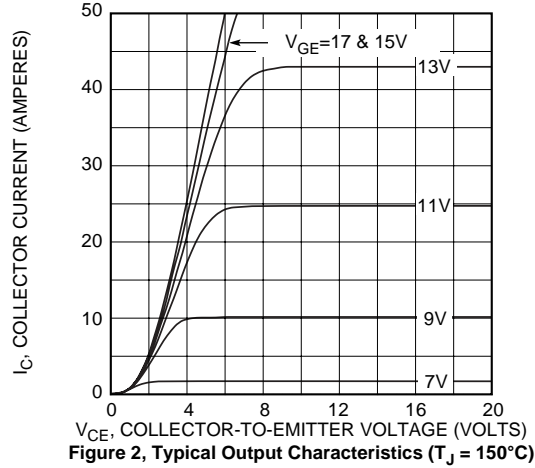


Figure 2, Typical Output Characteristics ( $T_J = 150^\circ\text{C}$ )

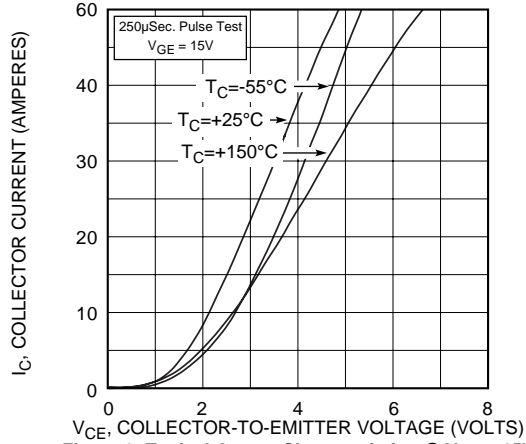


Figure 3, Typical Output Characteristics @  $V_{GE} = 15\text{V}$

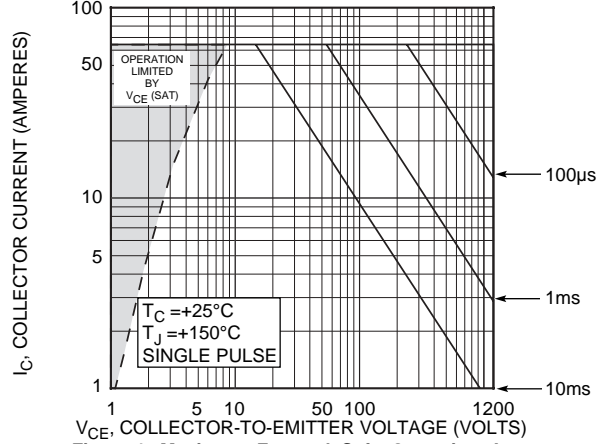


Figure 4, Maximum Forward Safe Operating Area

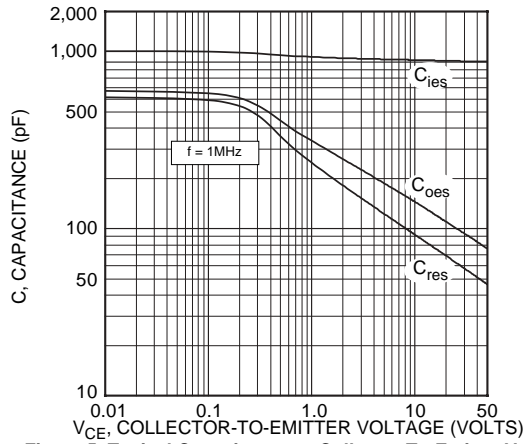


Figure 5, Typical Capacitance vs Collector-To-Emitter Voltage

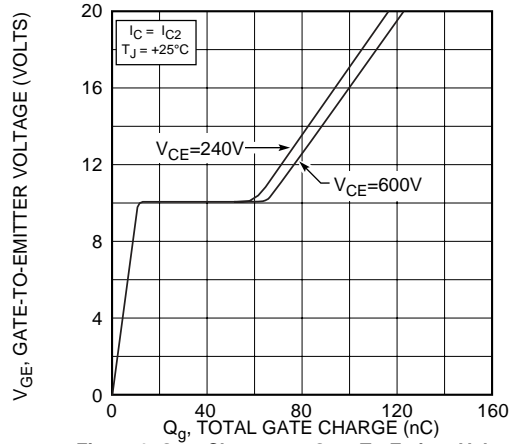


Figure 6, Gate Charges vs Gate-To-Emitter Voltage

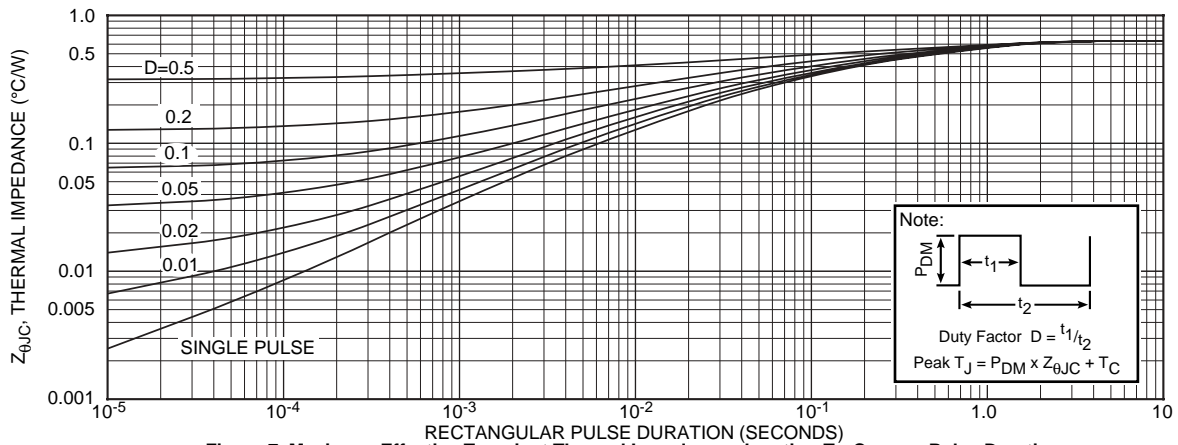


Figure 7, Maximum Effective Transient Thermal Impedance, Junction-To-Case vs Pulse Duration

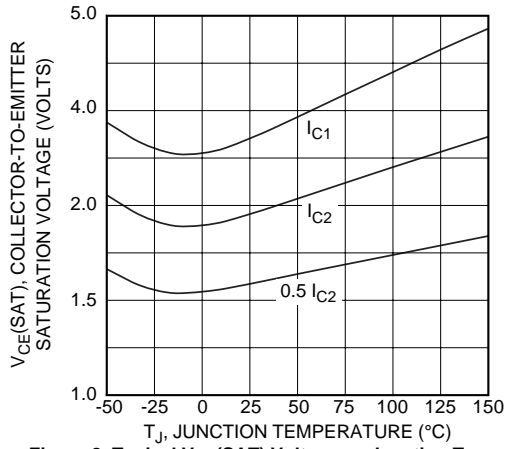


Figure 8, Typical  $V_{CE(SAT)}$  Voltage vs Junction Temperature

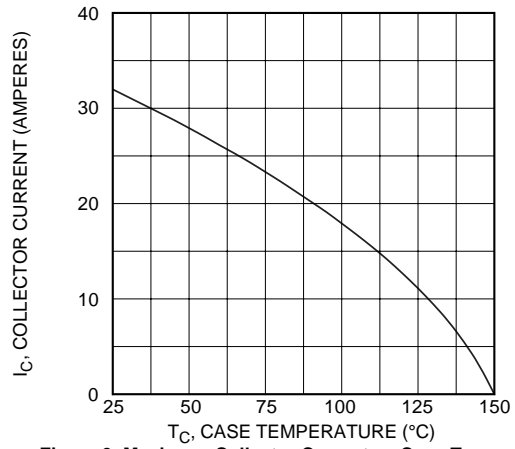


Figure 9, Maximum Collector Current vs Case Temperature

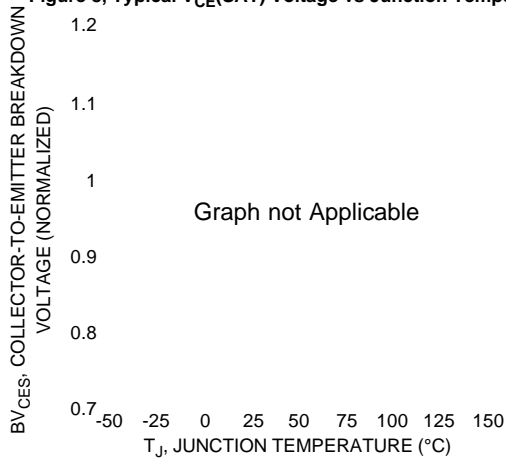


Figure 10, Breakdown Voltage vs Junction Temperature

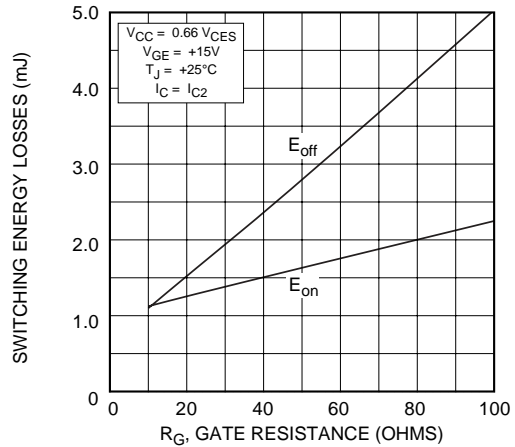


Figure 11, Typical Switching Energy Losses vs Gate Resistance

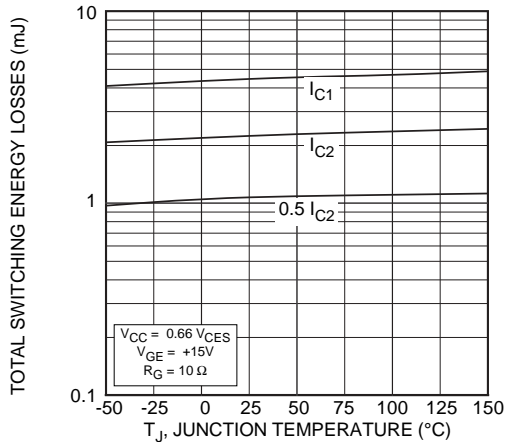


Figure 12, Typical Switching Energy Losses vs. Junction Temperature

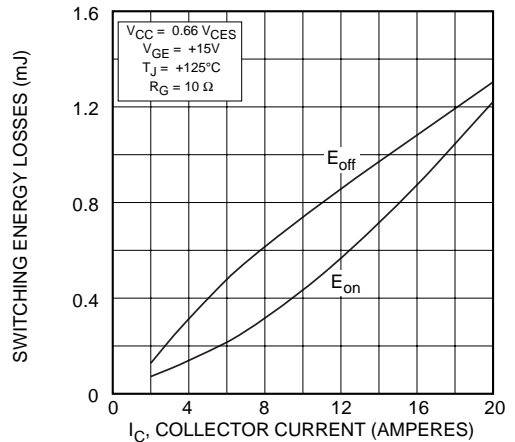


Figure 13, Typical Switching Energy Losses vs Collector Current

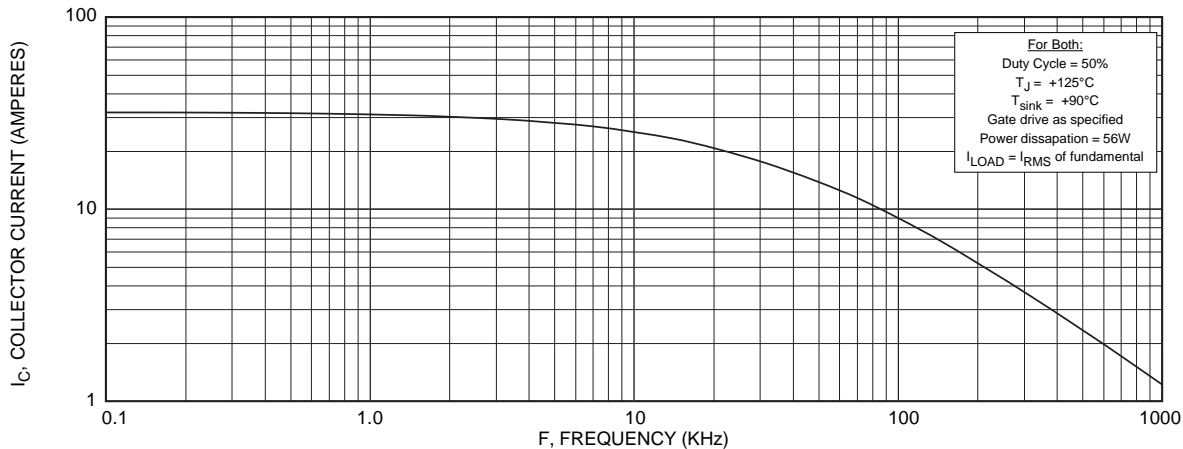


Figure 14, Typical Load Current vs Frequency

## 20GF120BRD/SRD

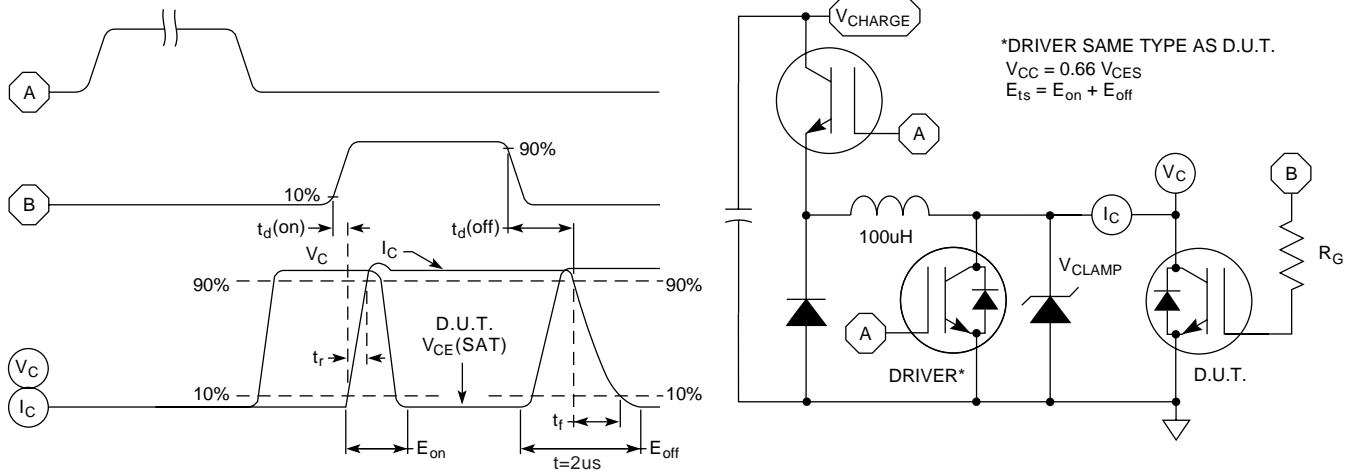


Figure 15, Switching Loss Test Circuit and Waveforms

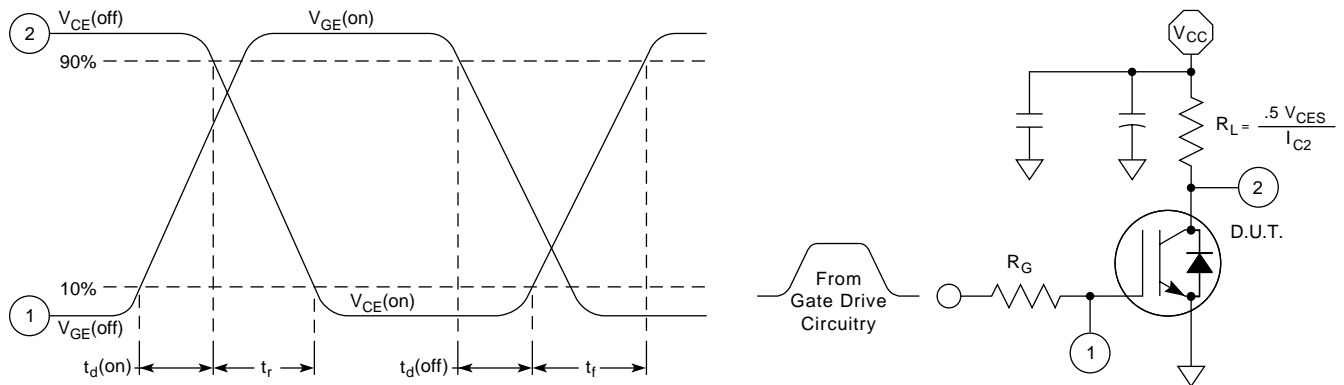


Figure 16, Resistive Switching Time Test Circuit and Waveforms

# ULTRAFAST SOFT RECOVERY PARALLEL DIODE

## MAXIMUM RATINGS (FRED)

All Ratings:  $T_C = 25^\circ\text{C}$  unless otherwise specified.

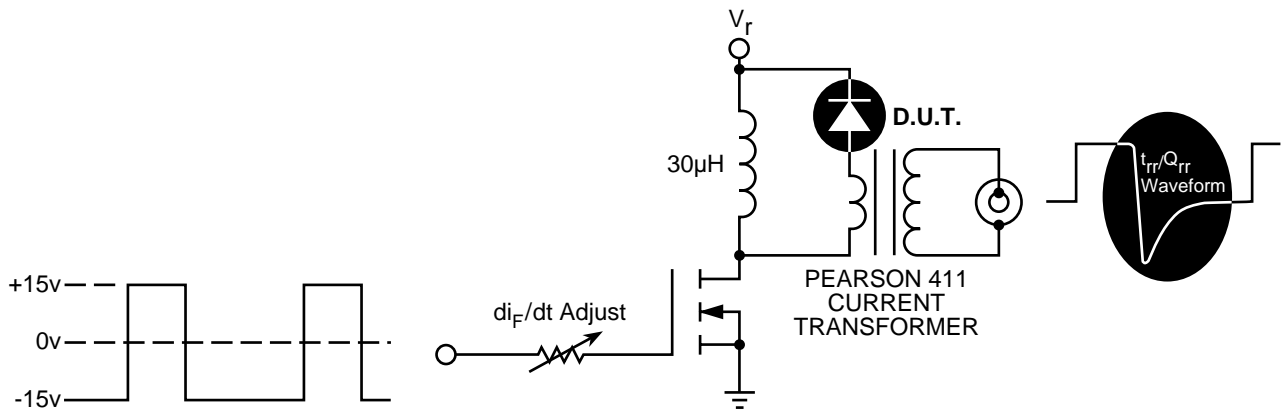
| Symbol        | Characteristic  | 20GF120BRD/SRD | UNIT |
|---------------|---|----------------|------|
| $I_{F_{AV}}$  | Maximum Average Forward Current ( $T_C = 100^\circ\text{C}$ , Duty Cycle = 0.5) | 30             | Amps |
| $I_{F_{RMS}}$ | RMS Forward Current   | 70             |      |
| $I_{F_{SM}}$  | Non-Repetive Forward Surge Current ( $T_J = 45^\circ\text{C}$ , 8.3 ms)         | 210            |      |

| Symbol | Characteristic / Test Conditions               | MIN   | TYP | MAX | UNIT  |
|--------|--|---|-----|-----|-------|
| $V_F$  | Maximum Forward Voltage                        | $I_F = 20\text{A}$                          |     | 2.3 | Volts |
|        |  | $I_F = 60\text{A}$                          |     | 2.0 |       |
|        |  | $I_F = 20\text{A}, T_J = 150^\circ\text{C}$ |     | 1.7 |       |
| $L_S$  | Series Inductance (Lead to Lead 5mm from Base) |   | 10  |     | nH    |

**DYNAMIC CHARACTERISTICS (FRED)**

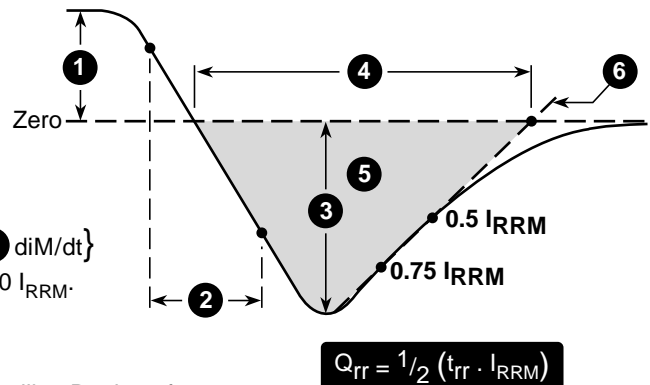
**20GF120BRD/SRD**

| Symbol     | Characteristic/ Test Conditions   | MIN                 | TYP  | MAX | UNIT       |
|------------|---|---------------------|------|-----|------------|
| $t_{rr1}$  | Reverse Recovery Time, $I_F = 1.0A$ , $di_F/dt = -15A/\mu S$ , $V_R = 30V$ , $T_J = 25^\circ C$ |                     | 70   | 85  | nS         |
| $t_{rr2}$  | Reverse Recovery Time   | $T_J = 25^\circ C$  | 70   |     |            |
| $t_{rr3}$  | $I_F = 20A$ , $di_F/dt = -240A/\mu S$ , $V_R = 650V$  | $T_J = 100^\circ C$ | 160  |     |            |
| $t_{fr1}$  | Forward Recovery Time   | $T_J = 25^\circ C$  | 255  |     | Volts      |
| $t_{fr2}$  | $I_F = 20A$ , $di_F/dt = 240A/\mu S$ , $V_R = 650V$   | $T_J = 100^\circ C$ | 255  |     |            |
| $I_{RRM1}$ | Reverse Recovery Current  | $T_J = 25^\circ C$  | 7    | 12  | Amps       |
| $I_{RRM2}$ | $I_F = 20A$ , $di_F/dt = -240A/\mu S$ , $V_R = 650V$  | $T_J = 100^\circ C$ | 12   | 20  |            |
| $Q_{rr1}$  | Recovery Charge   | $T_J = 25^\circ C$  | 660  |     | nC         |
| $Q_{rr2}$  | $I_F = 20A$ , $di_F/dt = -240A/\mu S$ , $V_R = 650V$  | $T_J = 100^\circ C$ | 1640 |     |            |
| $V_{fr1}$  | Forward Recovery Voltage  | $T_J = 25^\circ C$  | 15   |     | Volts      |
| $V_{fr2}$  | $I_F = 20A$ , $di_F/dt = 240A/\mu S$ , $V_R = 650V$   | $T_J = 100^\circ C$ | 20   |     |            |
| $diM/dt$   | Rate of Fall of Recovery Current  | $T_J = 25^\circ C$  | 245  |     | A/ $\mu S$ |
|            | $I_F = 20A$ , $di_F/dt = -240A/\mu S$ , $V_R = 650V$ (See Figure 18)                            | $T_J = 100^\circ C$ | 160  |     |            |



**Figure 17, Diode Reverse Recovery Test Circuit and Waveforms**

- ❶  $I_F$  - Forward Conduction Current
- ❷  $di_F/dt$  - Current Slew Rate, Rate of Forward Current Change Through Zero Crossing.
- ❸  $I_{RRM}$  - Peak Reverse Recovery Current.
- ❹  $t_{rr}$  - Reverse Recovery Time Measured from Point of  $I_F$  Current Falling Through Zero to a Tangent Line {❻  $diM/dt$ } Extrapolated Through Zero Defined by 0.75 and 0.50  $I_{RRM}$ .
- ❺  $Q_{rr}$  - Area Under the Curve Defined by  $I_{RRM}$  and  $t_{rr}$ .
- ❻  $diM/dt$  - Maximum Rate of Current Change During the Trailing Portion of  $t_{rr}$ .



**Figure 18, Diode Reverse Recovery Waveform and Definitions**

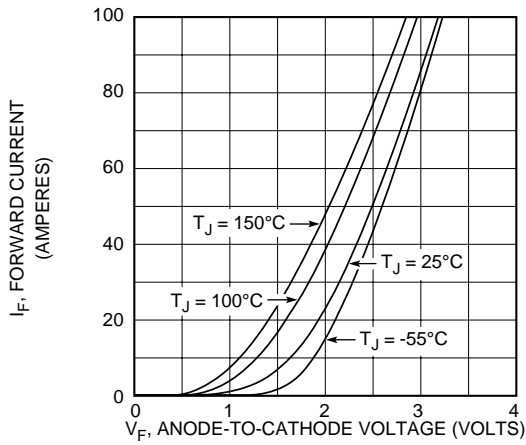


Figure 19, Forward Voltage Drop vs Forward Current

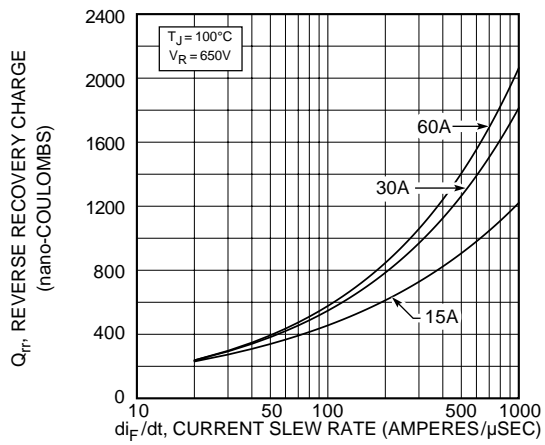


Figure 20, Reverse Recovery Charge vs Current Slew Rate

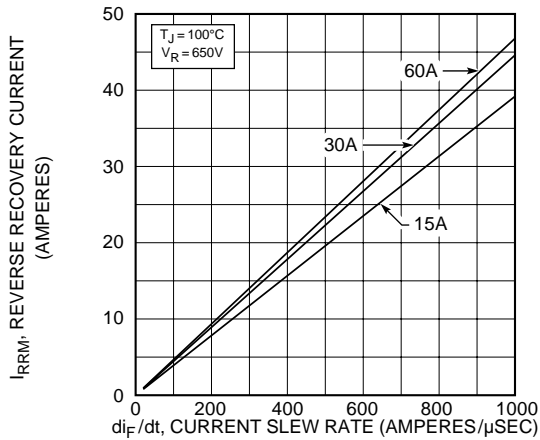


Figure 21, Reverse Recovery Current vs Current Slew Rate

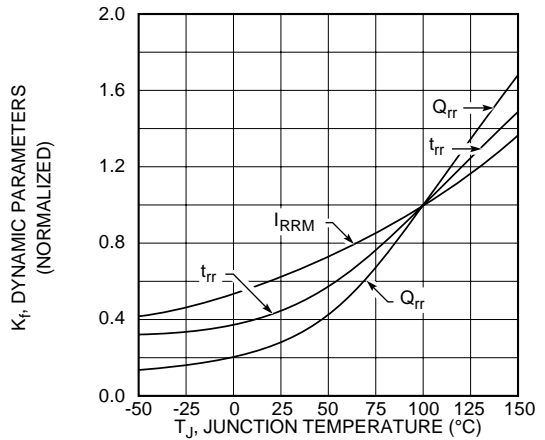


Figure 22, Dynamic Parameters vs Junction Temperature

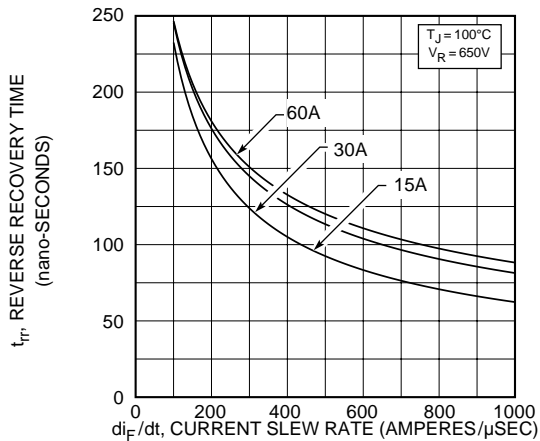


Figure 23, Reverse Recovery Time vs Current Slew Rate

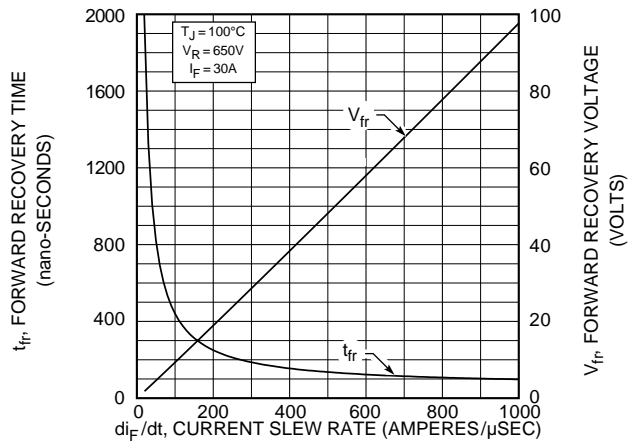


Figure 24, Forward Recovery Voltage/Time vs Current Slew Rate

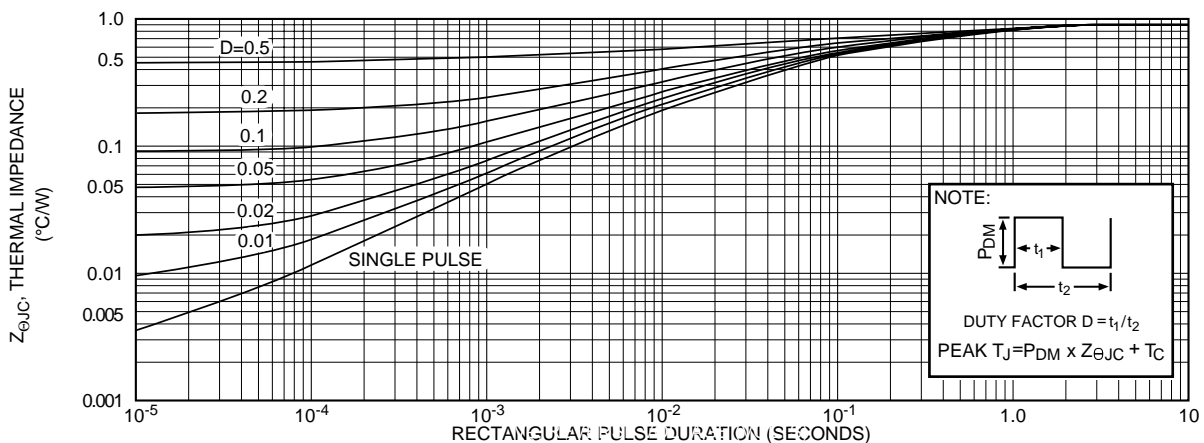
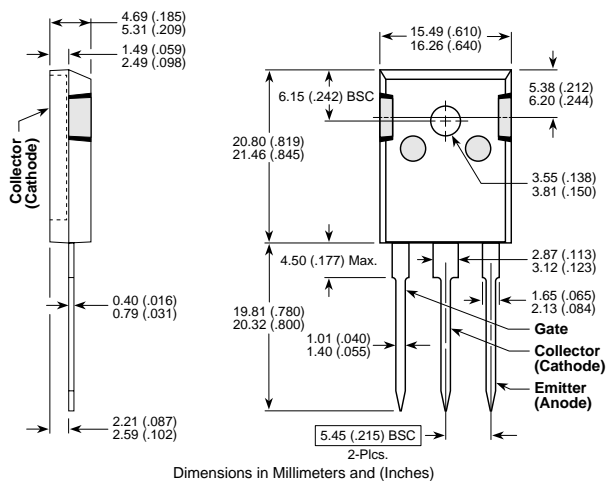
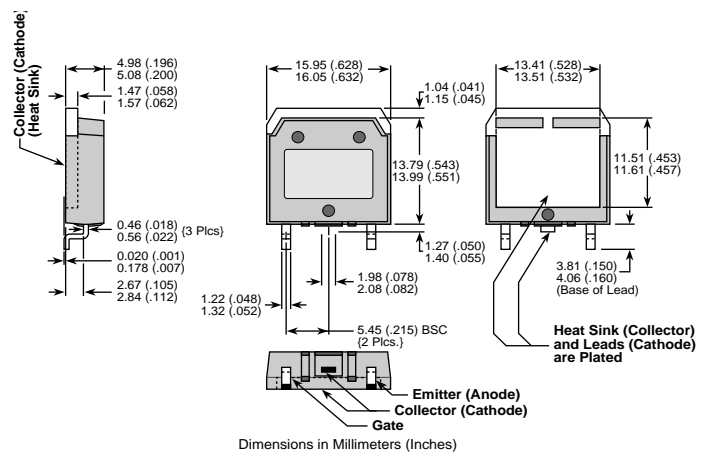


Figure 25, Maximum Effective Transient Thermal Impedance, Junction-To-Case vs Pulse Duration

**TO-247 Package Outline**



**D<sup>3</sup>PAK Package Outline**





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[IGW40N60H3FKSA1](#) [STGB15H60DF](#) [STGFW20V60DF](#) [STGFW30V60DF](#) [STGFW40V60F](#) [STGWA25H120DF2](#) [FGB3236\\_F085](#)  
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